



Material Content Data Sheet



Sales Product Name		ESD207-B1-02ELS E6327		Issued		20. July 2018		
MA#		MA001119986						
Package		PG-TSSLP-2-3		Weight*		0.21 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.17		1669	
	noble metal	gold	7440-57-5	0.001	0.65		6466	
	inorganic material	silicon	7440-21-3	0.010	4.79	5.61	47923	56058
leadframe	non noble metal	nickel	7440-02-0	0.108	51.68	51.68	516905	516905
wire	non noble metal	copper	7440-50-8	0.002	0.74	0.74	7379	7379
encapsulation	organic material	carbon black	1333-86-4	0.000	0.19		1879	
	plastics	epoxy resin	-	0.011	5.46		54556	
	inorganic material	silicondioxide	60676-86-0	0.067	31.98	37.63	319801	376236
leadfinish	noble metal	gold	7440-57-5	0.004	1.76	1.76	17637	17637
plating	noble metal	palladium	7440-05-3	0.001	0.61		6116	
	noble metal	gold	7440-57-5	0.004	1.97	2.58	19669	25785
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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